

# PDTB123T series

PNP 500 mA, 50 V resistor-equipped transistors;  
R1 = 2.2 k $\Omega$ , R2 = open

Rev. 03 — 16 November 2009

Product data sheet

## 1. Product profile

### 1.1 General description

PNP Resistor-Equipped Transistors (RET) family.

Table 1. Product overview

Type number	Package			NPN complement
	NXP	JEITA	JEDEC	
PDTB123TK	SOT346	SC-59A	TO-236	PDTD123TK
PDTB123TS <sup>[1]</sup>	SOT54	SC-43A	TO-92	PDTD123TS
PDTB123TT	SOT23	-	TO-236AB	PDTD123TT

[1] Also available in SOT54A and SOT54 variant packages (see [Section 2](#)).

### 1.2 Features

- Built-in bias resistors
- Simplifies circuit design
- 500 mA output current capability
- Reduces component count
- Reduces pick and place costs

### 1.3 Applications

- Digital application in automotive and industrial segments
- Controlling IC inputs
- Cost-saving alternative for BC807 series in digital applications
- Switching loads

### 1.4 Quick reference data

Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V <sub>CEO</sub>	collector-emitter voltage	open base	-	-	-50	V
I <sub>O</sub>	output current (DC)		-	-	-500	mA
R1	bias resistor 1 (input)		1.54	2.2	2.86	k $\Omega$

## 2. Pinning information

Table 3. Pinning

Pin	Description	Simplified outline	Symbol
<b>SOT54</b>			
1	input (base)		
2	output (collector)		
3	GND (emitter)		
<b>SOT54A</b>			
1	input (base)		
2	output (collector)		
3	GND (emitter)		
<b>SOT54 variant</b>			
1	input (base)		
2	output (collector)		
3	GND (emitter)		
<b>SOT23; SOT346</b>			
1	input (base)		
2	GND (emitter)		
3	output (collector)		

### 3. Ordering information

Table 4. Ordering information

Type number	Package		
	Name	Description	Version
PDTB123TK	SC-59A	plastic surface mounted package; 3 leads	SOT346
PDTB123TS <sup>[1]</sup>	SC-43A	plastic single-ended leaded (through hole) package; 3 leads	SOT54
PDTB123TT	-	plastic surface mounted package; 3 leads	SOT23

[1] Also available in SOT54A and SOT54 variant packages (see [Section 2](#) and [Section 9](#)).

### 4. Marking

Table 5. Marking codes

Type number	Marking code <sup>[1]</sup>
PDTB123TK	F1
PDTB123TS	TB123TS
PDTB123TT	*1U

[1] \* = -: made in Hong Kong  
 \* = p: made in Hong Kong  
 \* = t: made in Malaysia  
 \* = W: made in China

### 5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CBO}$	collector-base voltage	open emitter	-	-50	V
$V_{CEO}$	collector-emitter voltage	open base	-	-50	V
$V_{EBO}$	emitter-base voltage	open collector	-	-5	V
$V_I$	input voltage				
	positive		-	+5	V
	negative		-	-12	V
$I_O$	output current (DC)		-	-500	mA
$P_{tot}$	total power dissipation	$T_{amb} \leq 25\text{ °C}$	<a href="#">[1]</a>		
	SOT346		-	250	mW
	SOT54		-	500	mW
	SOT23		-	250	mW
$T_{stg}$	storage temperature		-65	+150	°C
$T_j$	junction temperature		-	150	°C
$T_{amb}$	ambient temperature		-65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

## 6. Thermal characteristics

**Table 7. Thermal characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1]			
	SOT346		-	-	500	K/W
	SOT54		-	-	250	K/W
	SOT23		-	-	500	K/W

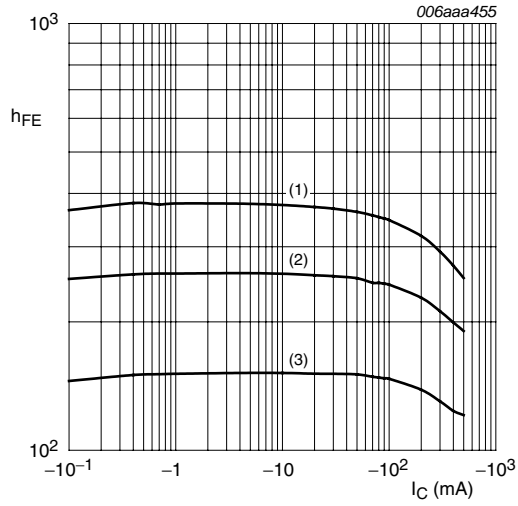
[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

## 7. Characteristics

**Table 8. Characteristics**

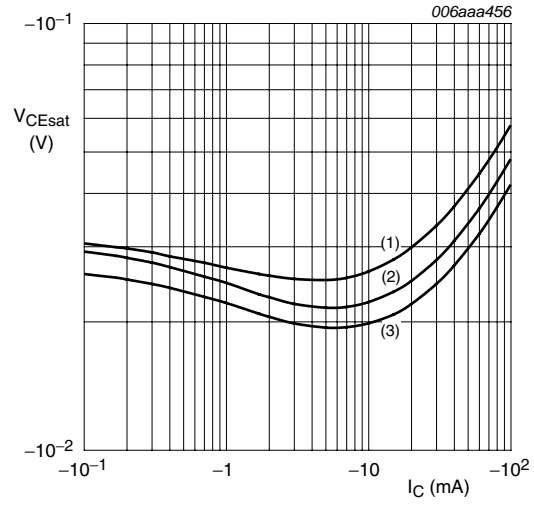
$T_{amb} = 25\text{ }^{\circ}\text{C}$  unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$I_{CBO}$	collector-base cut-off current	$V_{CB} = -40\text{ V}; I_E = 0\text{ A}$	-	-	-100	nA
		$V_{CB} = -50\text{ V}; I_E = 0\text{ A}$	-	-	-100	nA
$I_{CEO}$	collector-emitter cut-off current	$V_{CE} = -50\text{ V}; I_B = 0\text{ A}$	-	-	-0.5	$\mu\text{A}$
$I_{EBO}$	emitter-base cut-off current	$V_{EB} = -5\text{ V}; I_C = 0\text{ A}$	-	-	-100	nA
$h_{FE}$	DC current gain	$V_{CE} = -5\text{ V}; I_C = -50\text{ mA}$	100	250	-	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = -50\text{ mA}; I_B = -2.5\text{ mA}$	-	-	-0.3	mV
R1	bias resistor 1 (input)		1.54	2.2	2.86	k $\Omega$
$C_c$	collector capacitance	$V_{CB} = -10\text{ V}; I_E = i_e = 0\text{ A}; f = 100\text{ MHz}$	-	11	-	pF



$V_{CE} = -5\text{ V}$   
 (1)  $T_{amb} = 100\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = -40\text{ °C}$

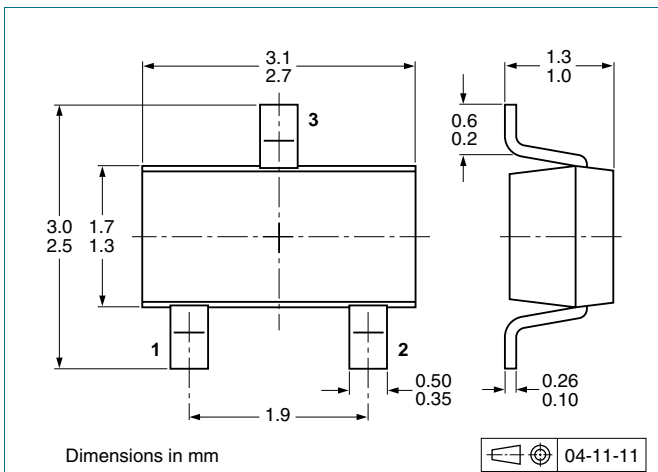
**Fig 1. DC current gain as a function of collector current; typical values**



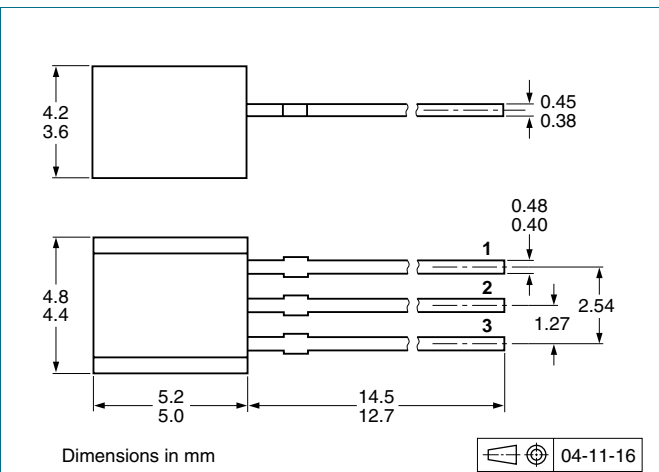
$I_C/I_B = 20$   
 (1)  $T_{amb} = 100\text{ °C}$   
 (2)  $T_{amb} = 25\text{ °C}$   
 (3)  $T_{amb} = -40\text{ °C}$

**Fig 2. Collector-emitter saturation voltage as a function of collector current; typical values**

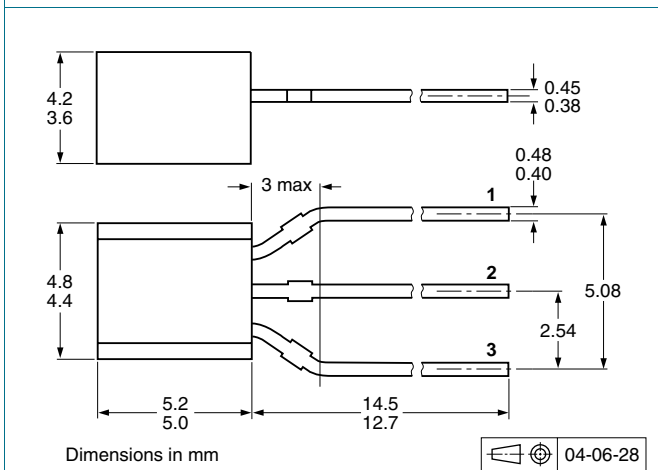
## 8. Package outline



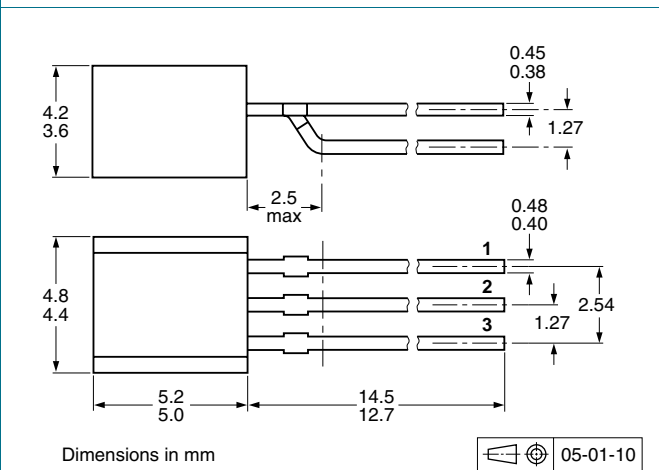
**Fig 3. Package outline SOT346 (SC-59A/TO-236)**



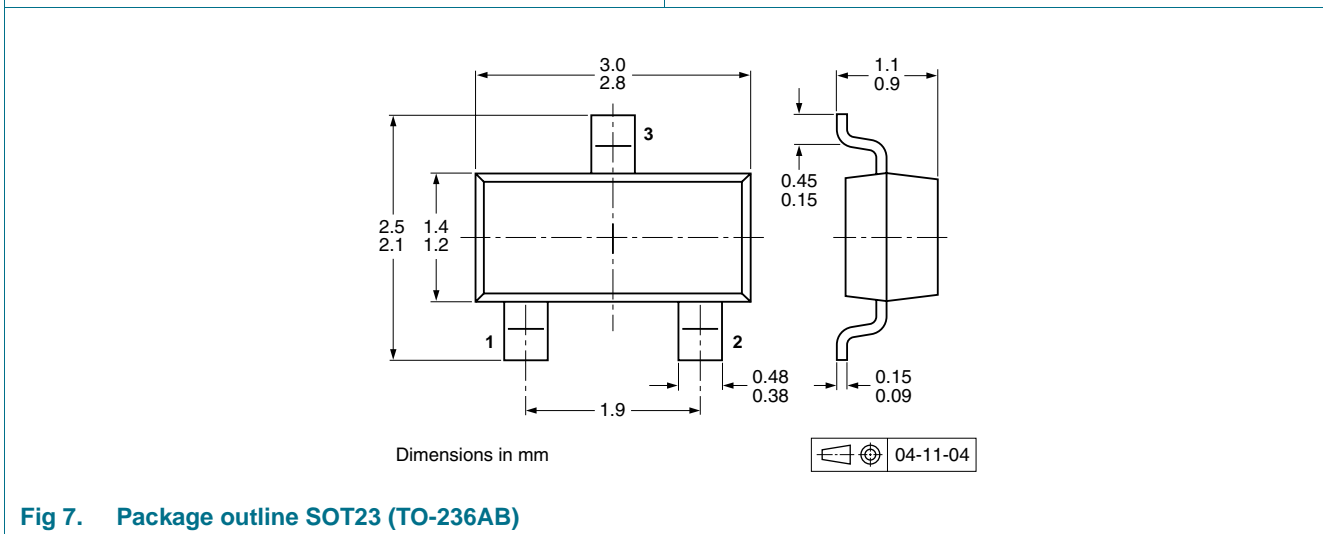
**Fig 4. Package outline SOT54 (SC-43A/TO-92)**



**Fig 5. Package outline SOT54A**



**Fig 6. Package outline SOT54 variant**



**Fig 7. Package outline SOT23 (TO-236AB)**

## 9. Packing information

**Table 9. Packing methods**

The indicated -xxx are the last three digits of the 12NC ordering code.<sup>[1]</sup>

Type number	Package	Description	Packing quantity		
			3000	5000	10000
PDTB123TK	SOT346	4 mm pitch, 8 mm tape and reel	-115	-	-135
PDTB123TS	SOT54	bulk, straight leads	-	-412	-
	SOT54A	tape and reel, wide pitch	-	-	-116
		tape ammopack, wide pitch	-	-	-126
	SOT54 variant	bulk, delta pinning	-	-112	-
PDTB123TT	SOT23	4 mm pitch, 8 mm tape and reel	-215	-	-235

[1] For further information and the availability of packing methods, see [Section 12](#).

## 10. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PDTB123T_SER_3	20091116	Product data sheet	-	PDTB123T_SER_2
Modifications:	<ul style="list-style-type: none"><li>This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content.</li></ul>			
PDTB123T_SER_2	20050804	Product data sheet	-	PDTB123TK_1
PDTB123TK_1	20050519	Product data sheet	-	-



## 11. Legal information

### 11.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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